g GE Industrial Systems	TEST and OPERATING PROCEDURE	
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	QUALITY REP: Robert Dwell	
TITLE: DS3800HFPC TEST PROCEDURE		PROCEDURE: LOU-GED-DS3800HFPC-B

1. INTRODUCTORY DESCRIPTION

A. This procedure establishes the methods for testing a DS3800HFPC
B. Environmental ranges: 70 +/- 10 Deg. F. with 20-75% R.H.
C. Unit warm-up/stabilization period requirement: NONE
D. Personnel using this procedure are expected to have a high degree of confidence and expertise in related testing and calibration procedures.
E. Procedures not explained here are considered to be understood as common practice.

2. TEST EQUIPMENT VERIFICATION

A. Verify the accuracy of the standard(s) used in the repair/calibration process by evidence of recent calibration labeling affixed to the test equipment.
B. All measurement standards used in this procedure shall be traceable to the NATIONAL INSTITUTE of STANDARDS and TECHNOLOGY (N.I.S.T.) and shall have the accuracy, stability, range and resolution required for the intended use.
C. Unless otherwise specified, the collective uncertainty of the Measurement Standard(s) shall not exceed twenty five percent of the acceptable tolerance for each characteristic being calibrated.
D. All deviations shall be documented.

3. EQUIPMENT CLEANING

A. All equipment cleaning will be performed as instructed in the GEES SOP Sec. 14.0

4. EQUIPMENT INSPECTION

A. The following criteria should be used as a guideline or basis for the inspection process of the this unit:
    1. Wires broken or cracked.
    2. Terminal strips / connectors broken or cracked.
    3. Loose wires.
    4. Components visually damaged.
    5. Capacitors leaking.
    6. Solder joint, cold.
    7. Circuit board discolored or burned.
    8. Printed wire runs burned or damaged.

5. REVISION HISTORY

Revision	Date	Initials	Reason for Revision
A	10/14/94	EWR	Initial Procedure – After Verification
B	06/07/02	RKD	Added section 5 & 6, Changed procedure number
C			
D			
E			
F			
G			
H			
I			
J			
K			

6. REFERENCE DOCUMENTATION

- Reference: GEK
- Factory Procedure #

7. THEORY OF OPERATION

A. Refer to the DS3800HFPC Module information Bulletin(s) for theory of operation.

8. TEST EQUIPMENT TO BE USED

- (TWO)Fluke 9010A Microsystem Troubleshooter.
- Fluke Z80 Interface Pod
- Fluke 8088 Interface Pod
- FACLO 542 dumb terminal or equivelant
- (THREE) Data cables
- DS3800HFPC test fixture **H033521**
- Fluke software for testing a DS3800HFPC board (latest revision)
  Tape 1 MASTER: **SW2001** Tape 2 SLAVE: **SW2002**

9. FINAL TEST AND OPERATION PROCESS

✍NOTE: Avoid using water-based flux when repairing the board due to the fact that it is very conductive and the board will need to be washed and baked before retesting. In addition, before re-inserting any chip, use acetone to remove the excess flus on both sides of the UUT.

- Connect the required equipment as outlined in Figure 1.
- Install the UUT into the fixture and power on.
- Load and run the test software in both units and follow all instructions verbatum.

✍NOTE: Pay close attention to all pot settings.

8. SPECIAL INFORMATION

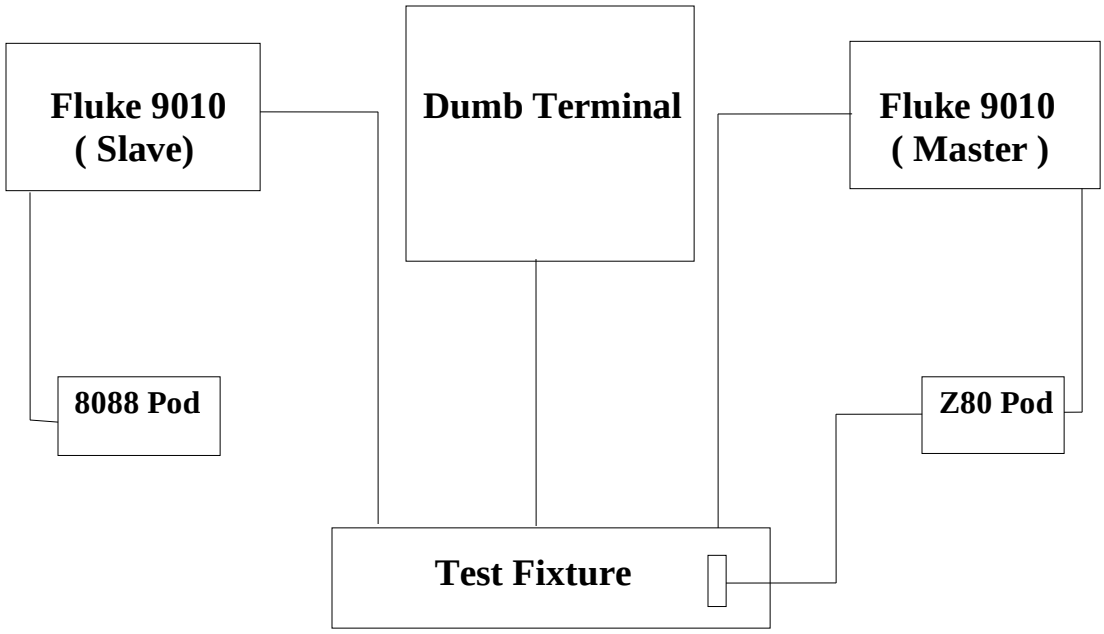

Figure 1

TEST WRITTEN BY: Eric Rouse **DATE:** 10/14/94

TEST VERIFIED BY: _____ **DATE:** _____